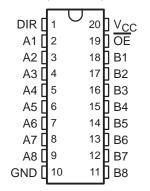
- Operates From 1.65 V to 3.6 V
- Inputs Accept Voltages to 5.5 V
- Max t_{pd} of 6.3 ns at 3.3 V
- Typical V_{OLP} (Output Ground Bounce)
 <0.8 V at V_{CC} = 3.3 V, T_A = 25°C
- Typical V_{OHV} (Output V_{OH} Undershoot)
 >2 V at V_{CC} = 3.3 V, T_A = 25°C
- I_{off} Supports Partial-Power-Down Mode Operation
- Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC})
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 1000-V Charged-Device Model (C101)

description/ordering information

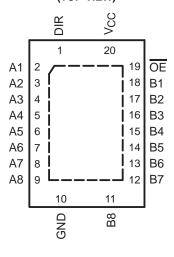
This octal bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVC245A is designed for asynchronous communication between data buses. The device transmits data from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can be used to disable the device so the buses are effectively isolated.

DB, DGV, DW, N, NS, OR PW PACKAGE (TOP VIEW)



RGY PACKAGE (TOP VIEW)



ORDERING INFORMATION

TA	PACKAGET	•	ORDERABLE PART NUMBER	TOP-SIDE MARKING
	PDIP – N	Tube of 20	SN74LVC245AN	SN74LVC245AN
	QFN – RGY	Reel of 1000	SN74LVC245ARGYR	LC245A
	COIC DW	Tube of 25	SN74LVC245ADW	11/00454
	SOIC – DW	Reel of 2000	SN74LVC245ADWR	LVC245A
	SOP - NS	Reel of 2000	SN74LVC245ANSR	LVC245A
-40°C to 85°C	SSOP – DB	Reel of 2000	SN74LVC245ADBR	LC245A
-40 C to 65 C		Tube of 70	SN74LVC245APW	
	TSSOP - PW	Reel of 2000	SN74LVC245APWR	LC245A
		Reel of 250	SN74LVC245APWT	
	TVSOP - DGV	Reel of 2000	SN74LVC245ADGVR	LC245A
	VFBGA – GQN	Reel of 1000	SN74LVC245AGQNR	LC245A
	VFBGA – ZQN (Pb-Free)	Reel of 1000	SN74LVC245AZQNR	L0240A

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

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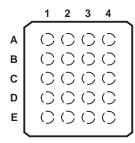
description/ordering information (continued)

To ensure the high-impedance state during power up or power down, $\overline{\text{OE}}$ should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of this device as a translator in a mixed 3.3-V/5-V system environment.

This device is fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

GQN OR ZQN PACKAGE (TOP VIEW)



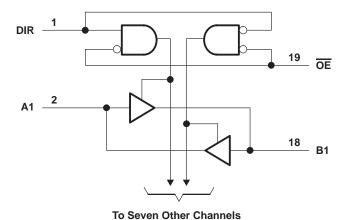
terminal assignments

	1	2	3	4
Α	A1	DIR	VCC	ŌĒ
В	А3	B2	A2	B1
С	A5	A4	B4	В3
D	A7	B6	A6	B5
Е	GND	A8	B8	B7

FUNCTION TABLE

INP	UTS	ODEDATION			
OE	DIR	OPERATION			
L	L	B data to A bus			
L	Н	A data to B bus			
Н	Χ	Isolation			

logic diagram (positive logic)



Pin numbers shown are for the DB, DGV, DW, N, NS, PW, and RGY packages.



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absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC}	–0.5 V to 6.5 V
Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	–0.5 V to 6.5 V
Voltage range applied to any output in the high or low state, V _O	
(see Notes 1 and 2)	$0.5 \text{ V to V}_{CC} + 0.5 \text{ V}$
Input clamp current, I _{IK} (V _I < 0)	
Output clamp current, I _{OK} (V _O < 0)	
Continuous output current, IO	±50 mA
Continuous current through V _{CC} or GND	±100 mA
Package thermal impedance, θ _{JA} (see Note 3): DB package	70°C/W
(see Note 3): DGV package	92°C/W
(see Note 3): DW package	58°C/W
(see Note 3): GQN/ZQN package	78°C/W
(see Note 3): N package	69°C/W
(see Note 3): NS package	60°C/W
(see Note 3): PW package	
(see Note 4): RGY package	
Storage temperature range, T _{stg}	–65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of V_{CC} is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51-7.
- 4. The package thermal impedance is calculated in accordance with JESD 51-5.



SN74LVC245A **OCTAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS SCAS218T - JANUARY 1993 - REVISED JULY 2004

recommended operating conditions (see Note 5)

			T _A = 25°C		-40°C ⁻	ΓΟ 85°C		
			MIN	MAX	MIN	MAX	UNIT	
.,	Ownerhouseltenes	Operating	1.65	3.6	1.65	3.6		
VCC	Supply voltage	Data retention only	1.5		1.5		٧	
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$	$0.65 \times V_{CO}$		$0.65 \times V_{CC}$,		
V_{IH}	High-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$	1.7		1.7		V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$	2		2			
		$V_{CC} = 1.65 \text{ V to } 1.95 \text{ V}$		$0.35 \times V_{\hbox{CC}}$		$0.35 \times V_{CC}$		
٧ _{IL}	Low-level input voltage	$V_{CC} = 2.3 \text{ V to } 2.7 \text{ V}$		0.7		0.7	V	
		$V_{CC} = 2.7 \text{ V to } 3.6 \text{ V}$		0.8		0.8		
VI	Input voltage		0	5.5	0	5.5	V	
٧o	Output voltage		0	Vcc	0	VCC	V	
		V _{CC} = 1.65 V		-4		-4		
1	High level code of compart	$V_{CC} = 2.3 \text{ V}$		-8		-8	A	
IOH	High-level output current	$V_{CC} = 2.7 \text{ V}$		-12		-12	mA	
		V _{CC} = 3 V		-24		-24		
		V _{CC} = 1.65 V		4		4		
lOL	Low lovel output ourrent	V _{CC} = 2.3 V		8		8	mA	
	Low-level output current	V _{CC} = 2.7 V		12		12		
		V _{CC} = 3 V		24		24		
Δt/Δν	Input transition rise or fall rate	•		10		10	ns/V	

NOTE 5: All unused inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST SOUDITIONS	.,	T _A = 2	25°C	-40°C TO 85°C		
		TEST CONDITIONS	VCC	MIN T	YP MAX	MIN	MAX	UNIT
		I _{OH} = -100 μA	1.65 V to 3.6 V	V _{CC} - 0.2		V _{CC} - 0.2	!	
		$I_{OH} = -4 \text{ mA}$	1.65 V	1.29		1.2		
		$I_{OH} = -8 \text{ mA}$	2.3 V	1.9		1.7		V
VOH		12 12	2.7 V	2.2		2.2		V
		I _{OH} = −12 mA	3 V	2.4		2.4		
		$I_{OH} = -24 \text{ mA}$	3 V	2.3		2.2		
		I _{OL} = 100 μA	1.65 V to 3.6 V		0.1		0.2	
		I _{OL} = 4 mA	1.65 V		0.24		0.45	V
VOL		I _{OL} = 8 mA	2.3 V		0.3		0.7	
		I _{OL} = 12 mA	2.7 V		0.4		0.4	
		I _{OL} = 24 mA	3 V		0.55		0.55	
IĮ	Control inputs	$V_{I} = 0 \text{ to } 5.5 \text{ V}$	3.6 V		±1		±5	μΑ
l _{off}		V_I or $V_O = 5.5 V$	0		±1		±10	μΑ
loz†		V _O = 0 to 5.5 V	3.6 V		±1		±10	μΑ
		V _I = V _{CC} or GND	0.01/		1		10	
Icc		$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\ddagger}$ $I_{\text{O}} = 0$	3.6 V		1		10	μΑ
ΔICC		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND	2.7 V to 3.6 V		500		500	μΑ
Ci	Control inputs	$V_I = V_{CC}$ or GND	3.3 V		4			pF
C _{io}	A or B ports	$V_I = V_{CC}$ or GND	3.3 V	,	5.5			pF

 $[\]ensuremath{^{\dagger}}$ For I/O ports, the parameter IOZ includes the input leakage current.

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1)

DADAMETER	FROM	то	V ₂ -	T,	Վ = 25° C	;	-40°C T(O 85°C	LINUT
PARAMETER	(INPUT)	(OUTPUT)	VCC	MIN	TYP	MAX	MIN	MAX	UNIT
			1.8 V ± 0.15 V	1	6	12.2	1	12.7	
	A su D	D on A	2.5 V ± 0.2 V	1	3.9	7.8	1	8.3	
^t pd	A or B	B or A	2.7 V	1	4.2	7.1	1	7.3	ns
			3.3 V ± 0.3 V	1.5	3.8	6.1	1.5	6.3	
	ŌĒ	A or B	1.8 V ± 0.15 V	1	7	14.8	1	15.3	ns
			2.5 V ± 0.2 V	1	4.5	10	1	10.5	
^t en			2.7 V	1	5.4	9.3	1	9.5	
			3.3 V ± 0.3 V	1.5	4.4	8.3	1.5	8.5	
	ŌĒ	A or B	1.8 V ± 0.15 V	1	7.8	16.5	1	17	ns
			2.5 V ± 0.2 V	1	4	9	1	9.5	
^t dis			2.7 V	1	4.4	8.3	1	8.5	
				3.3 V ± 0.3 V	1.7	4.1	7.3	1.7	7.5
t _{sk(o)}			3.3 V ± 0.3 V				·	1	ns



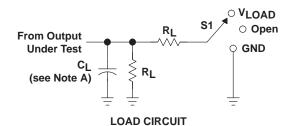
[‡] This applies in the disabled state only.

SN74LVC245A **OCTAL BUS TRANSCEIVER** WITH 3-STATE OUTPUTS SCAS218T - JANUARY 1993 - REVISED JULY 2004

operating characteristics, $T_A = 25^{\circ}C$

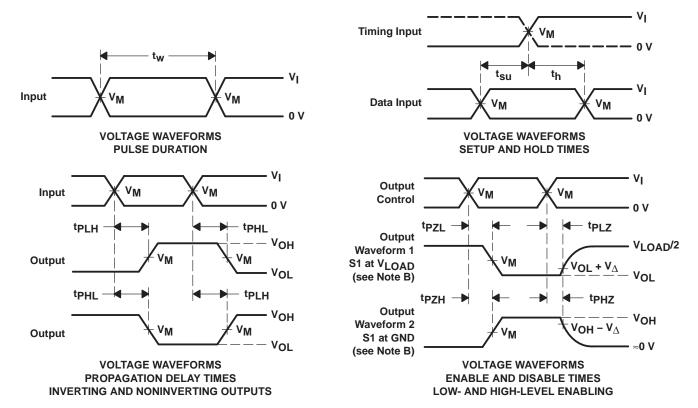
	PARAMETER			VCC	TYP	UNIT
				1.8 V	42	
C _{pd} Power dissipation capacitance per transceiver	Outputs enabled		2.5 V	43		
	Down discination conscitons now transcriver		f = 10 MHz	3.3 V	45	
	Power dissipation capacitance per transceiver			1.8 V	1	pF
		Outputs disabled		2.5 V	1	
				3.3 V	2	

PARAMETER MEASUREMENT INFORMATION



TEST	S 1
tPLH/tPHL	Open
tPLZ/tPZL	VLOAD
tPHZ/tPZH	GND

.,	INF	PUTS		V	•	-	.,
VCC	٧ _I	t _r /t _f	νM	VLOAD	CL	R_L	$oldsymbol{V}_\Delta$
1.8 V \pm 0.15 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	1 k Ω	0.15 V
2.5 V \pm 0.2 V	VCC	≤2 ns	V _{CC} /2	2×V _{CC}	30 pF	500 Ω	0.15 V
2.7 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V
3.3 V \pm 0.3 V	2.7 V	≤2.5 ns	1.5 V	6 V	50 pF	500 Ω	0.3 V



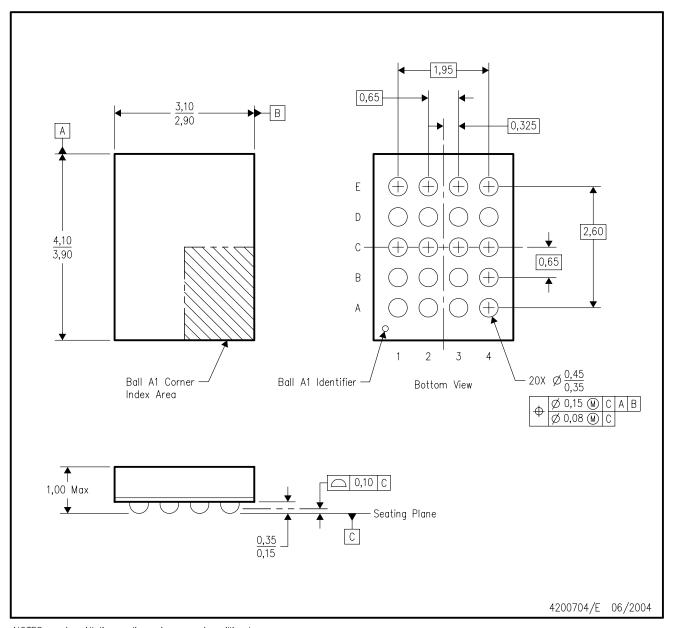
- NOTES: A. C_I includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, $Z_O = 50~\Omega$.
 - D. The outputs are measured one at a time, with one transition per measurement.
 - E. tpLz and tpHz are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.
 - H. All parameters and waveforms are not applicable to all devices.

Figure 1. Load Circuit and Voltage Waveforms



GQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



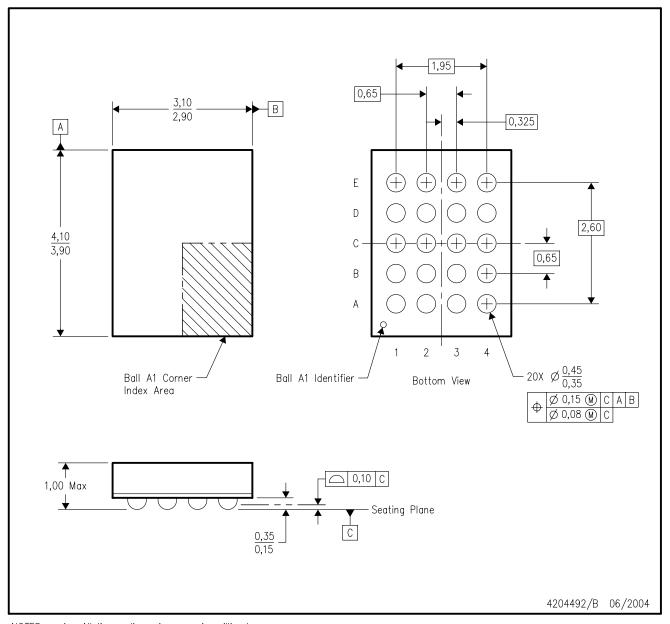
NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BC.
- D. This package is tin-lead (SnPb). Refer to the 20 ZQN package (drawing 4204492) for lead-free.



ZQN (R-PBGA-N20)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MO-225 variation BC.
- D. This package is lead-free. Refer to the 20 GQN package (drawing 4200704) for tin-lead (SnPb).



N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

16 PINS SHOWN



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
- The 20 pin end lead shoulder width is a vendor option, either half or full width.



DGV (R-PDSO-G**)

24 PINS SHOWN

PLASTIC SMALL-OUTLINE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15 per side.

D. Falls within JEDEC: 24/48 Pins – MO-153 14/16/20/56 Pins – MO-194



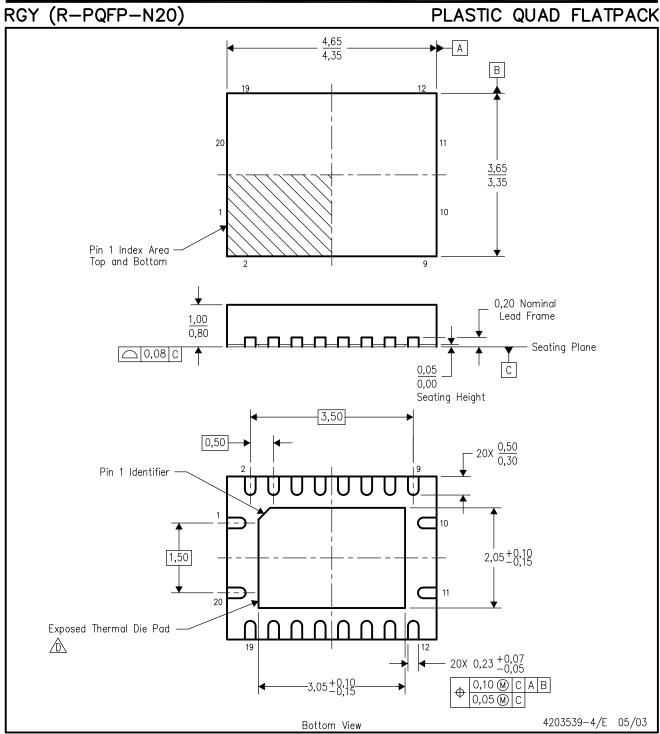
DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
- D. Falls within JEDEC MS-013 variation AC.





- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. QFN (Quad Flatpack No-Lead) package configuration.
- The package thermal performance may be enhanced by bonding the thermal die pad to an external thermal plane. This pad is electrically and thermally connected to the backside of the die and possibly selected ground leads.
- E. Package complies to JEDEC MO-241 variation BC.



MECHANICAL DATA

NS (R-PDSO-G**)

14-PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



- A. All linear dimensions are in millimeters.
- B. This drawing is subject to change without notice.
- C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.



DB (R-PDSO-G**)

PLASTIC SMALL-OUTLINE

28 PINS SHOWN



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-150

PW (R-PDSO-G**)

14 PINS SHOWN

PLASTIC SMALL-OUTLINE PACKAGE



NOTES: A. All linear dimensions are in millimeters.

B. This drawing is subject to change without notice.

C. Body dimensions do not include mold flash or protrusion not to exceed 0,15.

D. Falls within JEDEC MO-153

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